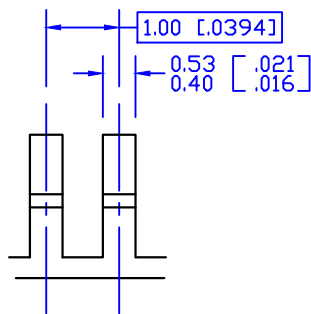
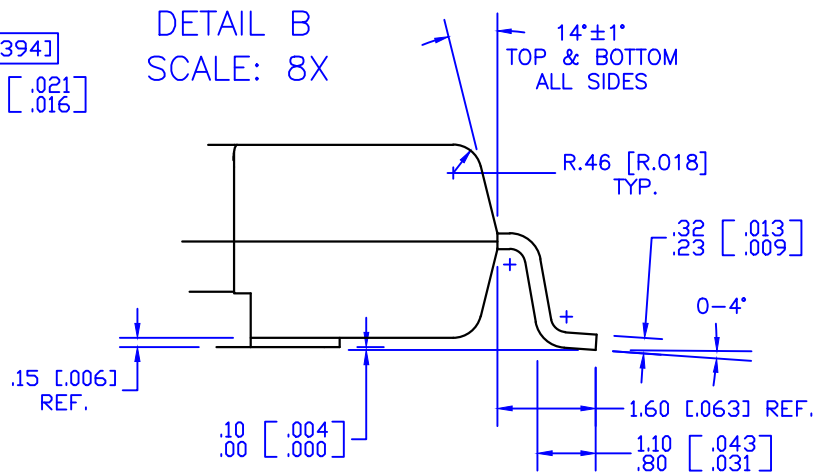


Surface Mount Layout



**DETAIL A
SCALE: 8X**



NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Dimple on lid & ESD triangle denote pin 1.
4. Pins & Heat Slug: CDA 194 copper with bismuth solder finish
5. Mold compound: MP-8000AN epoxy
6. Package weight: .086 oz. [2.44 g]
7. Suggested surface mount layout for reference only.

| |
|---|
| TOLERANCES - UNLESS OTHERWISE SPECIFIED |
| .XX = ±.01 [0.254] |
| .XXX = ±.005 [0.127] |
| ANG. = ±5° |



| | | | | |
|---|------------------------|----------------------|--------------------------|-----------|
| TITLE: JEDEC MO-166, 24-pin PSOP | | | | MODEL: |
| SUBJECT: PACKAGE OUTLINE | | | | DF |
| ENGINEER: J.MUTZ | DRAWN BY: J.FAY | DCA: 16322 | SH: 1 OF 1 | |
| FILENAME: DF | REV: F | DATE: 05AUG16 | | |

| | | |
|---------------------|---------------|----------------------|
| FILENAME: DF | REV: F | DATE: 05AUG16 |
|---------------------|---------------|----------------------|